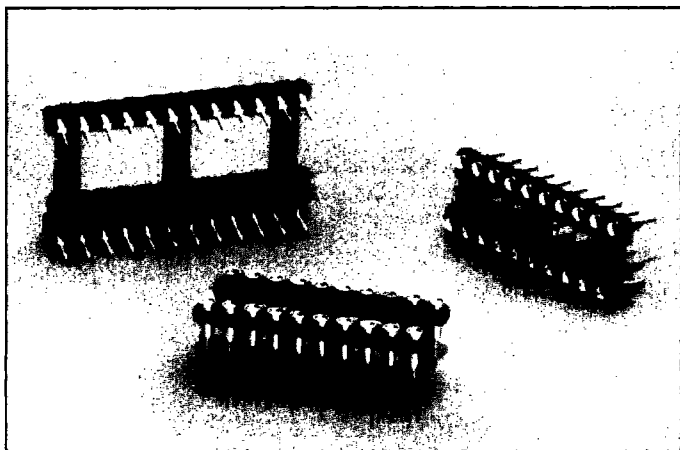


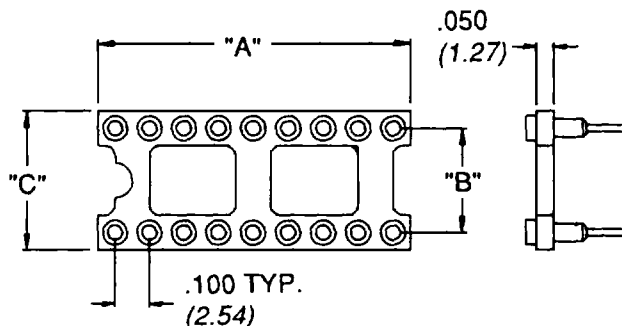
Thin Body Screw Machine Sockets

ICT Series

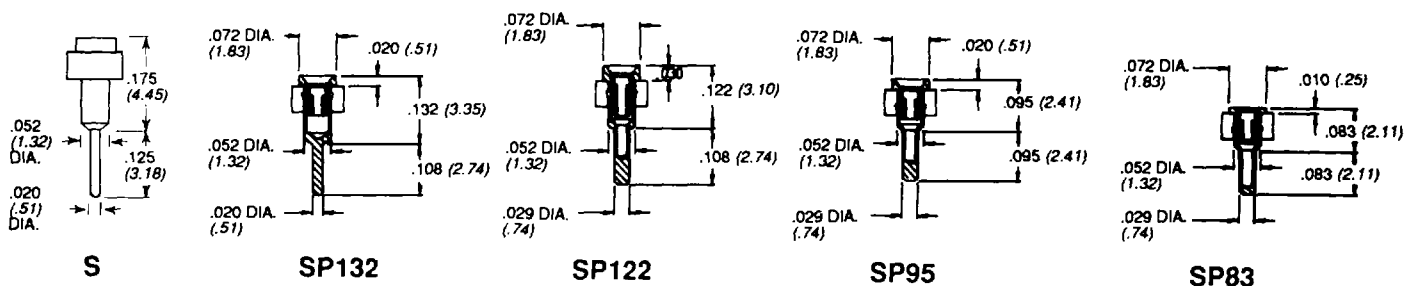


- Very low profile options available
- Four finger Beryllium Copper contact accepts short IC leads
- Pin socket design prevents solder wicking and flux entrapment
- Side/end stackable
- High temp IR compatible plastic

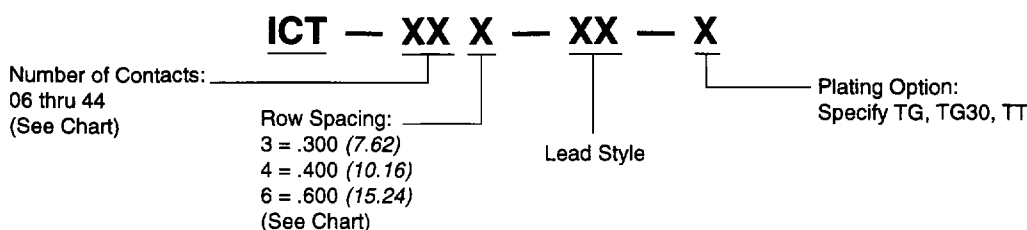
SOCKETS



Lead Style



How To Order ICT Series



Part Numbers

Number of Contacts	Description	Dimension A	Dimension B	Dimension C
6	ICT-063-X-X	.295 (7.49)	.300 (7.62)	.395 (10.03)
8	ICT-083-X-X	.395 (10.03)	.300 (7.62)	.395 (10.03)
14	ICT-143-X-X	.695 (17.65)	.300 (7.62)	.395 (10.03)
16	ICT-163-X-X	.795 (20.19)	.300 (7.62)	.395 (10.03)
18	ICT-183-X-X	.895 (22.73)	.300 (7.62)	.395 (10.03)
20	ICT-203-X-X	.995 (25.27)	.300 (7.62)	.395 (10.03)
22	ICT-224-X-X	1.095 (27.81)	.400 (10.16)	.495 (12.57)
24	ICT-243-X-X	1.195 (30.35)	.300 (7.62)	.395 (10.03)
24	ICT-246-X-X	1.195 (30.35)	.600 (15.24)	.695 (17.65)
28	ICT-286X-X	1.395 (35.43)	.600 (15.24)	.695 (17.65)
32	ICT-326-X-X	1.595 (40.51)	.600 (15.24)	.695 (17.65)
40	ICT-406-X-X	1.995 (50.67)	.600 (15.24)	.695 (17.65)
42	ICT-426-X-X	2.095 (53.21)	.600 (15.24)	.695 (17.65)

SOCKETS

Materials:

Body: High temp black nylon, glass-filled

Contacts: Beryllium Copper

Shell: Half Hard Brass

Acceptable Pin Sizes:

Diameter: .016" - .021" (.41 - .53)

Length:

SP132 = .080" - .110" (2.03 - 2.79)

SP122 = .105" - .170" (2.67 - 4.32)

SP95 = .080" - .155" (2.03 - 3.94)

SP83 = .070" - .145" (1.78 - 3.68)

S = .110" - .150" (2.79 - 3.81)

Mounting Information:

.020" Dia. Pin = .030" ± .002" PCB Hole
(.76 ± .05)

.029" Dia. Pin = .040" ± .002" PCB Hole
(1.1 ± .05)

Performance Characteristics:

Insertion Force: 16 ounces* max per contact
(*12 ounces max for SP122)

Withdrawal Force: 1.5 ounces* min per contact
(After 12 insertions)
*using .017 diameter pin

Capacitance: 1 picofarad maximum

Insulation Resistance: 5000 megohms minimum

Dielectric Withstanding Voltage: 500 volts AC

Current Rating: 1 Ampere

Flammability: UL 94H-B

Temperature Range: -65°C to + 125°C

Agency Approvals:



#E73746

Plating Description:

Suffix: TG = 10 μinch (.254 μm) minimum
Gold on contact area.
200 μinch (5.08 μm) minimum
Tin/Lead on terminal area.

TG30 = 30 μinch (.762 μm) minimum
Gold on contact area.
200 μinch (5.08 μm) minimum
Tin/Lead in terminal area.

TT = 150 μinch (3.81 μm) minimum
Tin/Lead on contact area.
200 μinch (5.08 μm) minimum
Tin/Lead on terminal area.

All options include: 50 μinch (1.27 μm)
minimum Nickel underplate.